

Components, Systems, and Grid Interface Challenges Related to Solid-State Transformers in Emerging Applications

CURRENT 2024 Industry Conference

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Outline

- Delta-at-a-Glance
- Solid-State-Transformers for Emerging Applications
 - DOE DC Fast Charging Demonstration
 - Datacenter Power Distribution
- Key Component: MV Transformer
- Take Aways

Delta Electronics at-a-Glance

To provide innovative, clean and energy-efficient solutions for a better tomorrow

Global provider of power and thermal management solutions

#1

- power supply manufacturer

\$12.89 B

- revenue in 2022

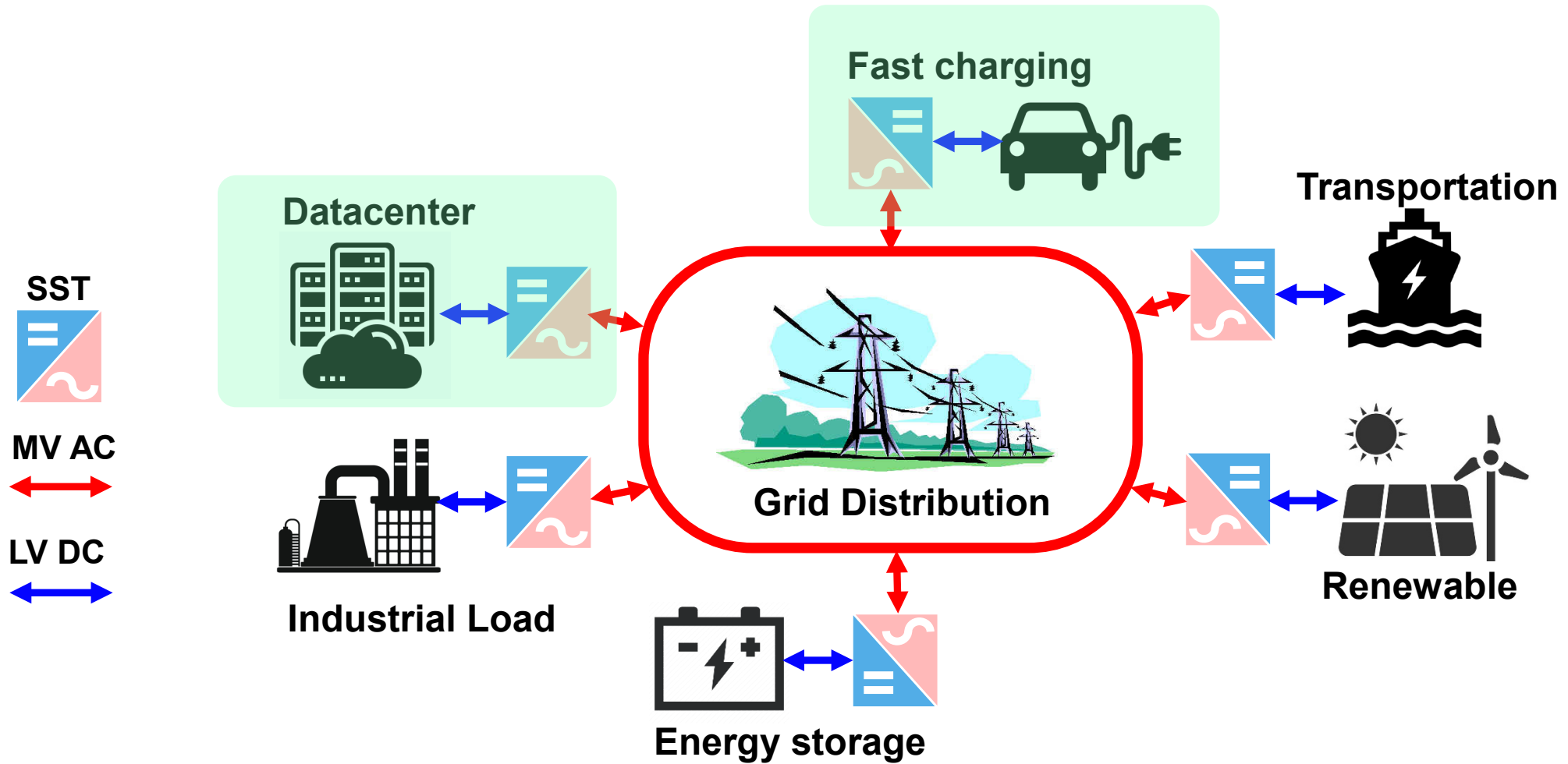
>8%

- of revenue invested on R&D

21.05 M tons

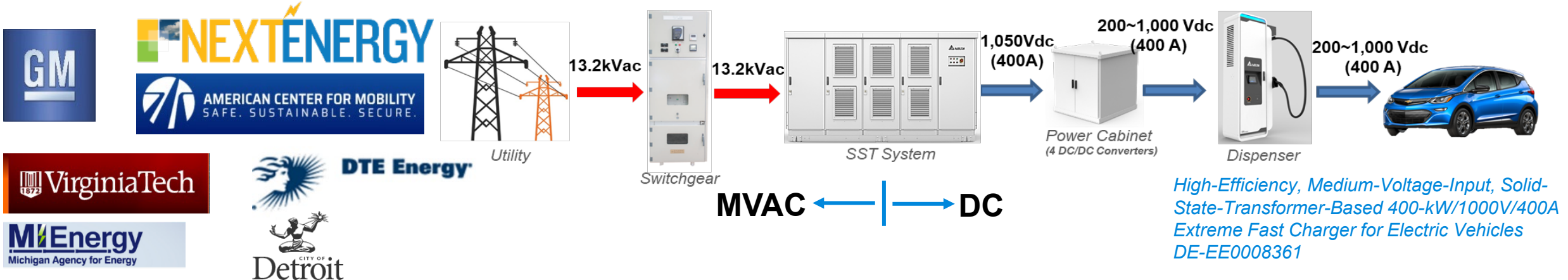
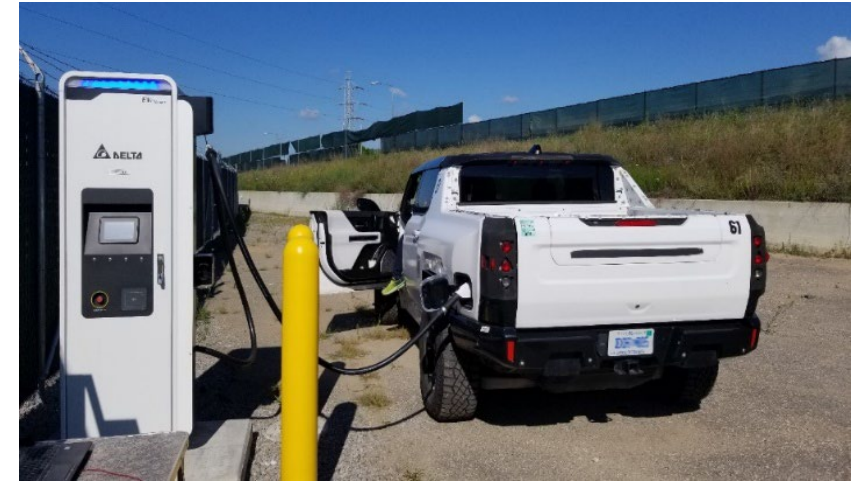
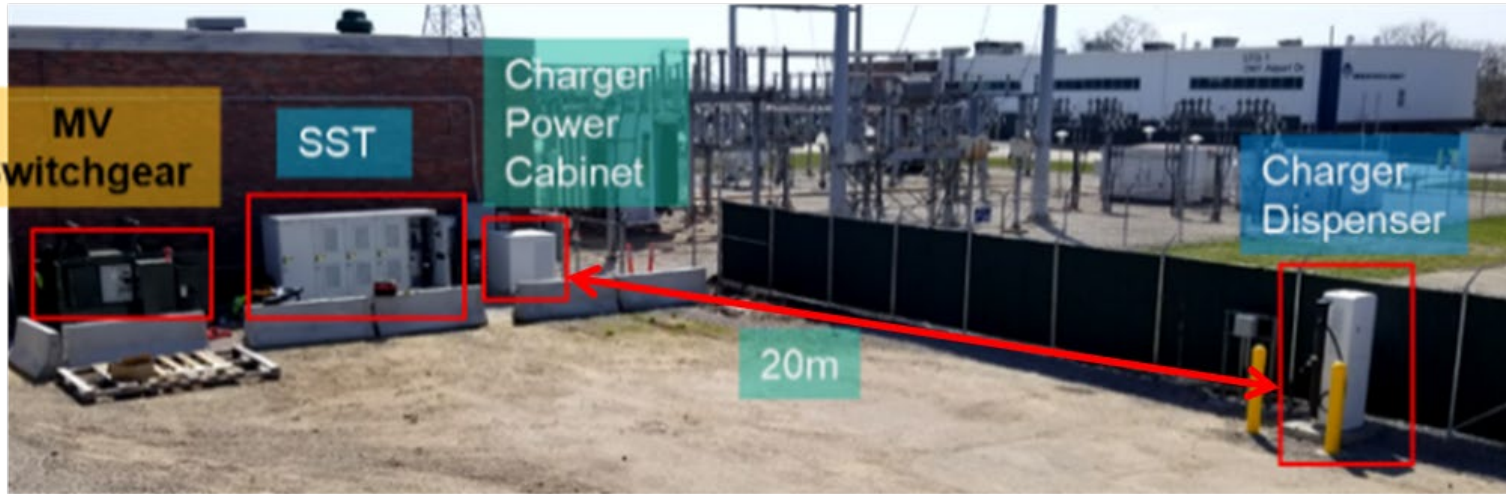
- of carbon emissions reduction from 2010 to 2022

Solid-State-Transformers (SST) Applications



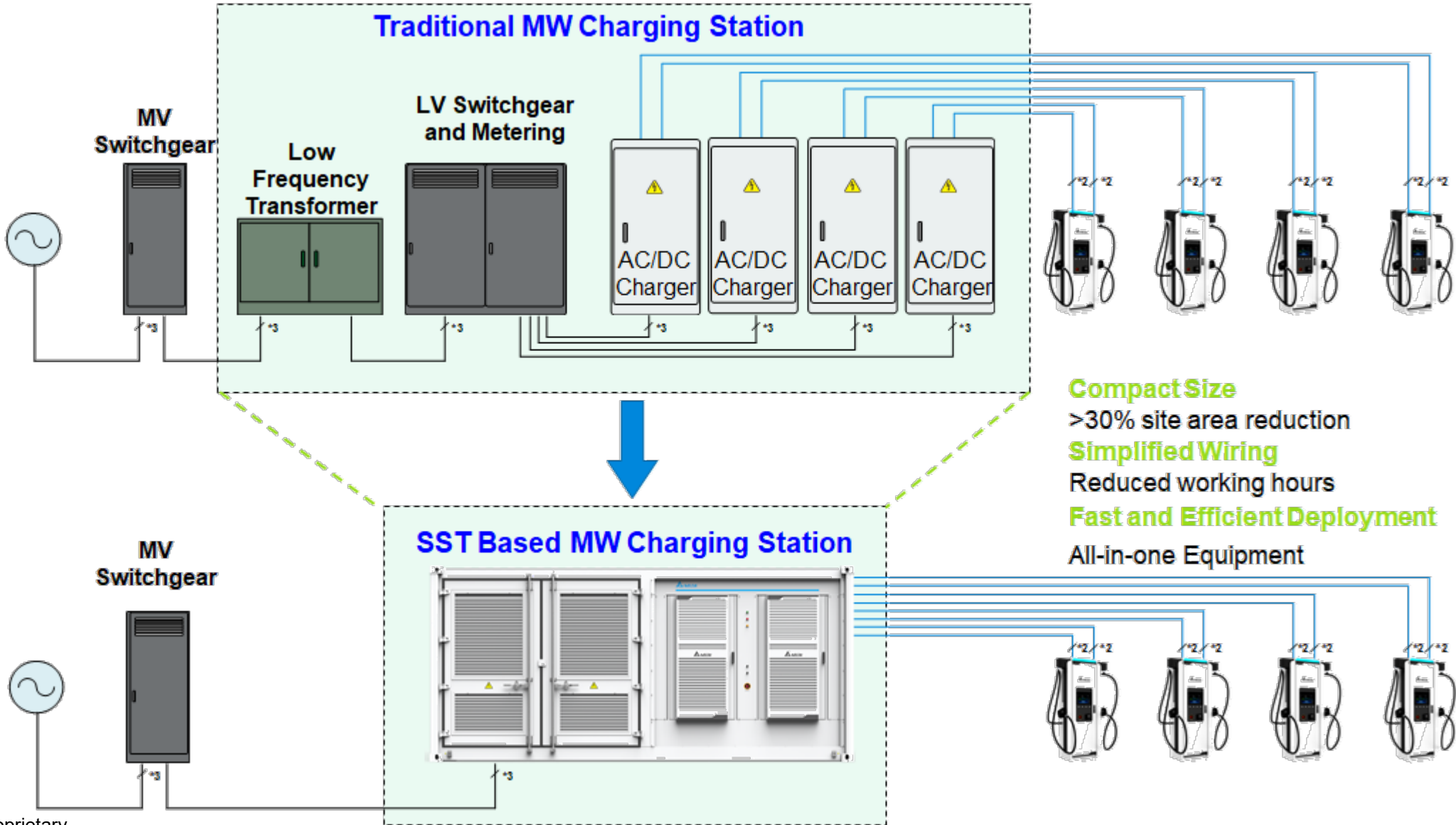
SST is an enabling technology for emerging applications

SST for EV Charging Applications



- Successfully commissioned a DOE-sponsored project in Detroit in cooperation with our partners on a 13.8 kV_{ac}, 400 kW, 400 A_{dc} single point charging station, November 2022

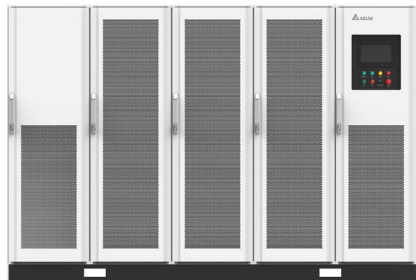
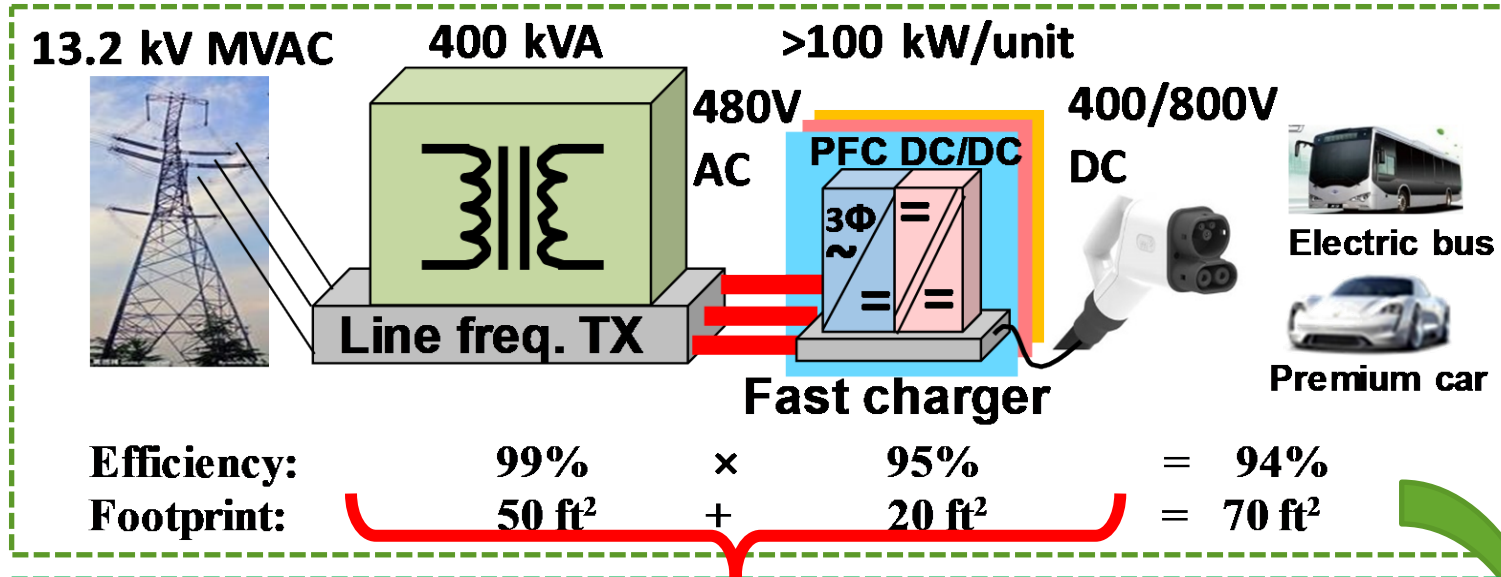
Value Proposition - SST Charging Station



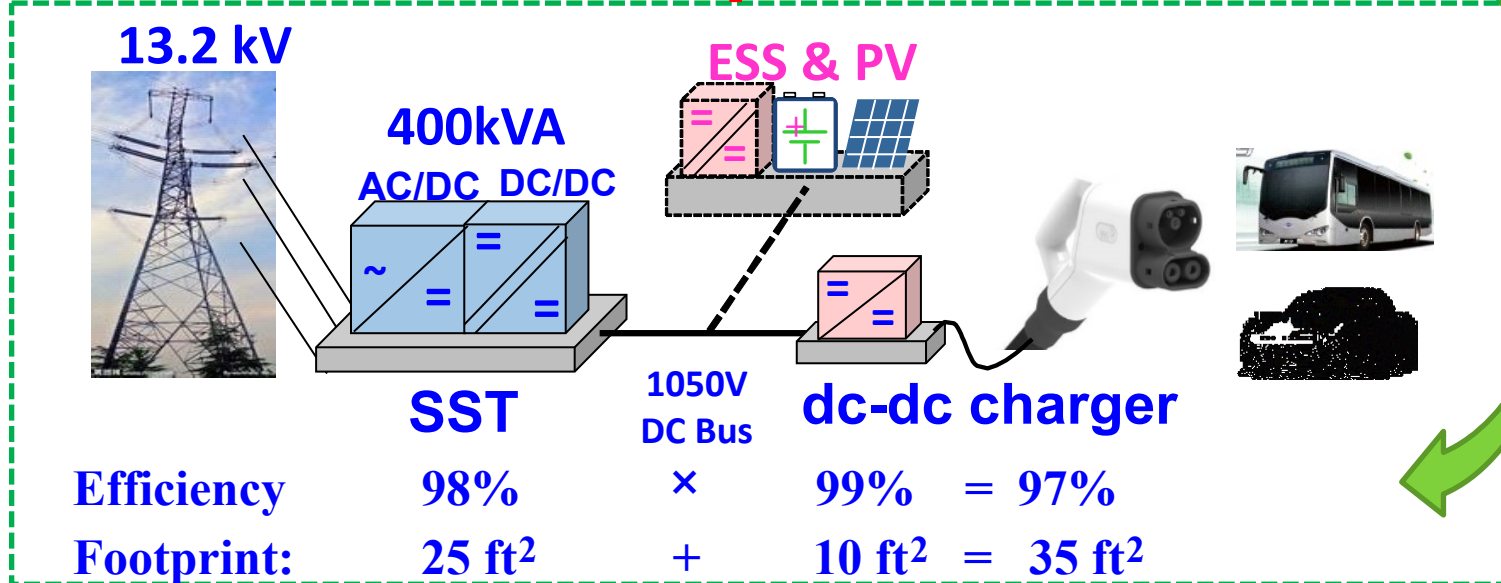
Line Frequency Transformer vs SST



Line Freq. Transformer

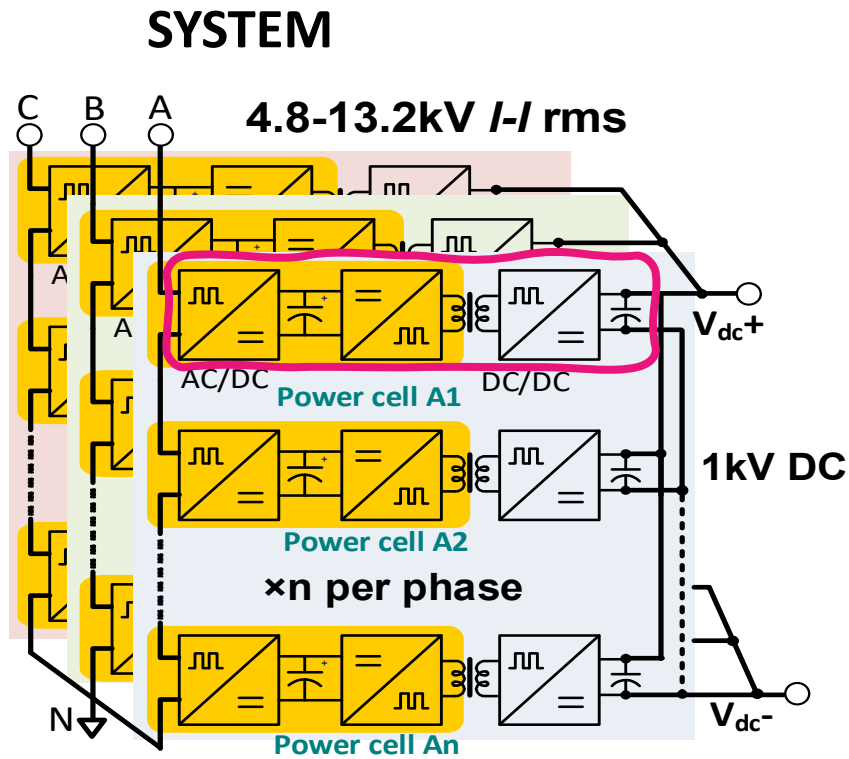


SST



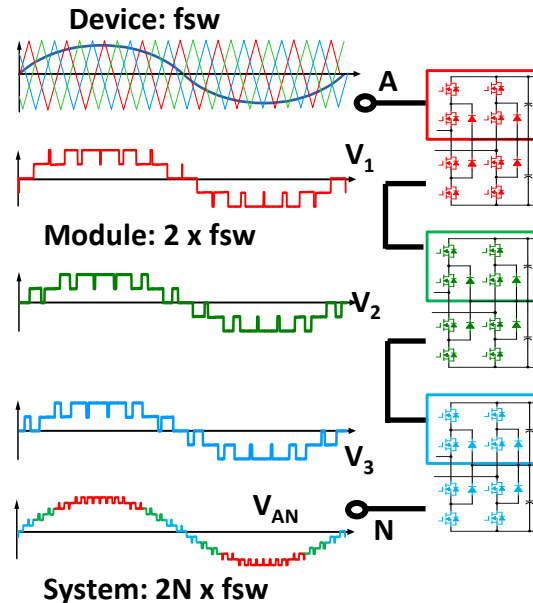
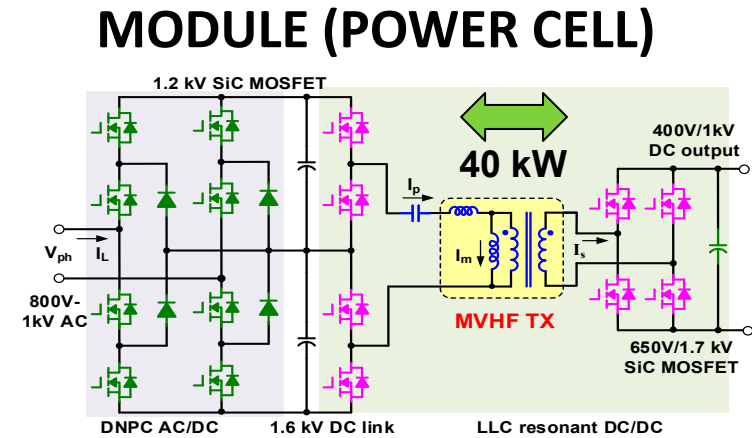
3% Eff. Improved
Up to 50% Space Saving

SST Architecture



Cascaded multilevel topology:

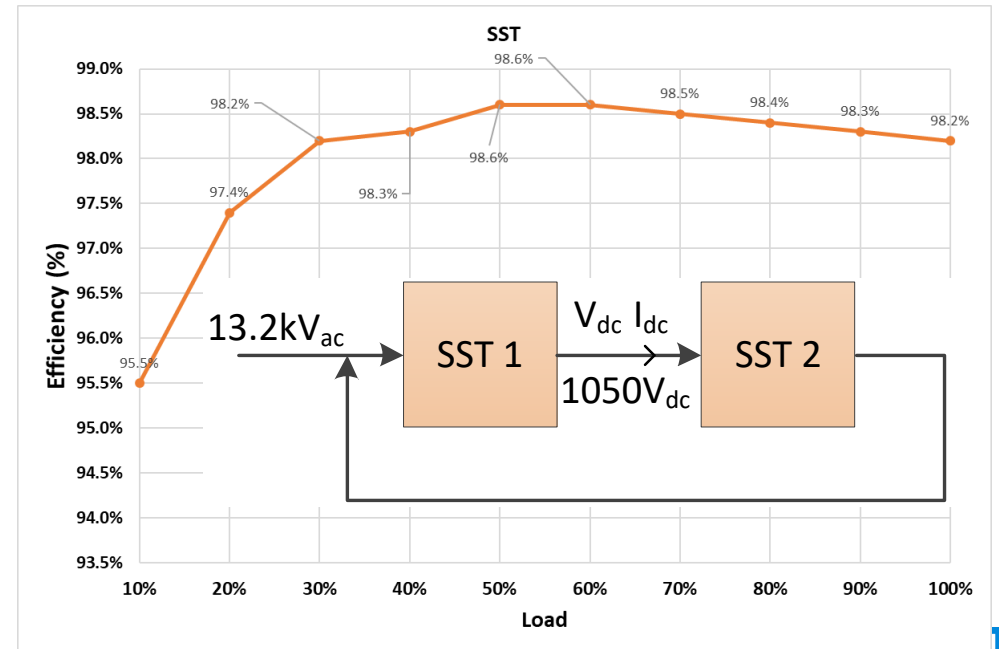
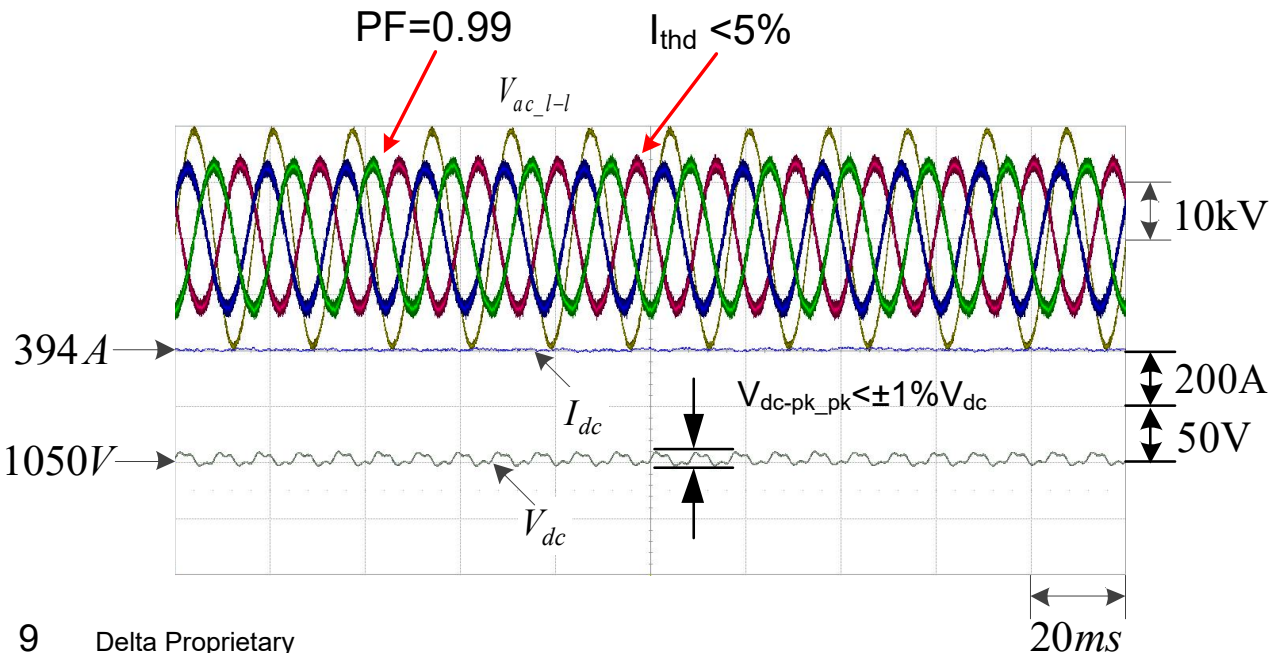
- Modular architecture and scalable
- Series-input, parallel-output (SIPO) module connection
- Interleaved input operation
 - Increases effective frequency and lowers THD
- Redundant operation possibility



Interleaved Input Operation

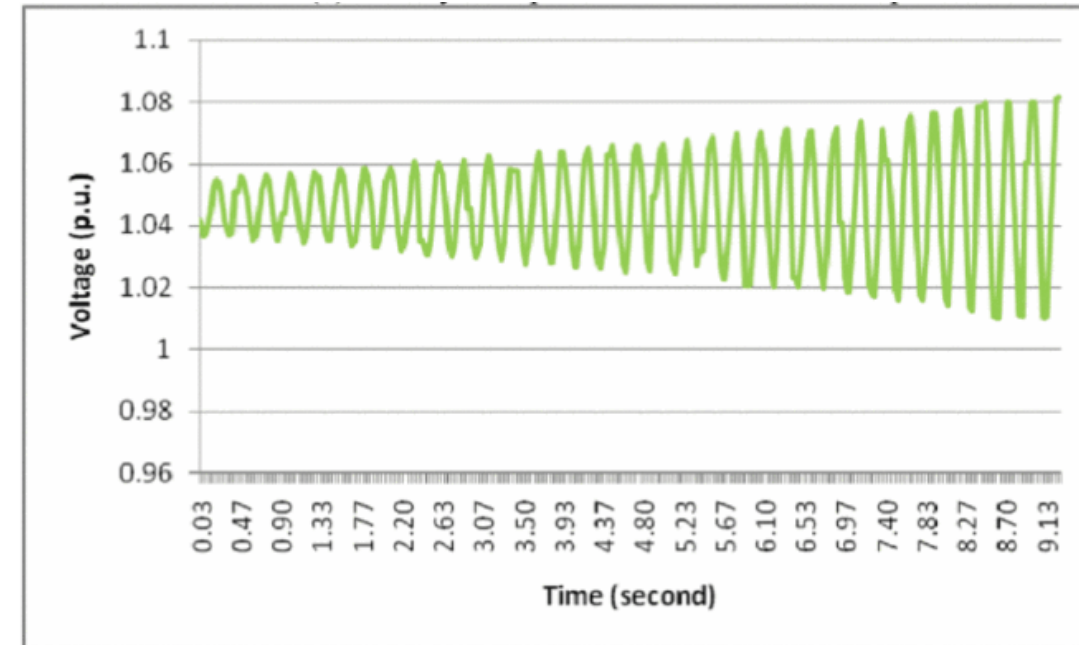
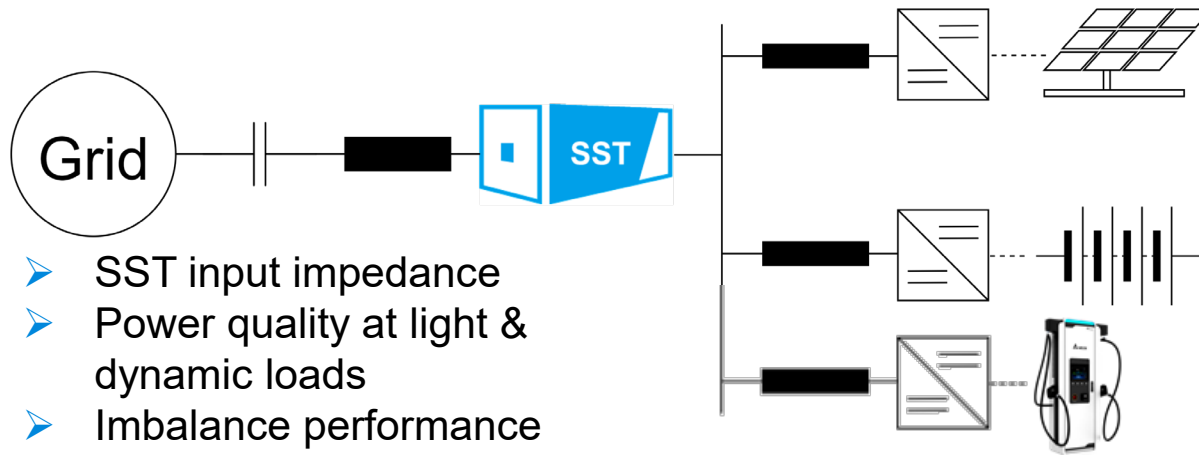
SST System Integration Test

- ▶ Back-to-Back Test Setup
 - Bidirectional Power Flow
- ▶ AC Input 13.2 kV / 410kW
 - PF: ± 0.99 @ 50%~100% Load
 - THDi < 5% @ 50%~100% Load
 - Efficiency: **98.6% @ 50% Load**
98.2% @ 100% Load



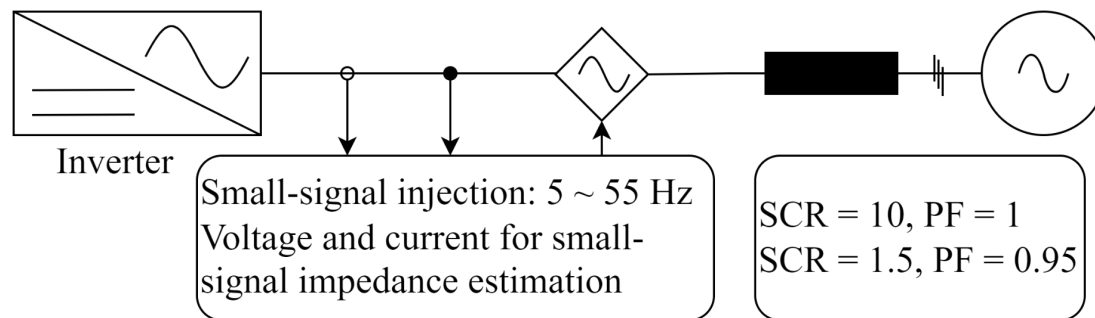
Sub-Synchronous Oscillations

DC-Coupled PV and BESS Hybrid Power Plant



(b) Un-damped oscillations at high output

ERCOT PGRR-08, Sub-synchronous Frequency Scan Test

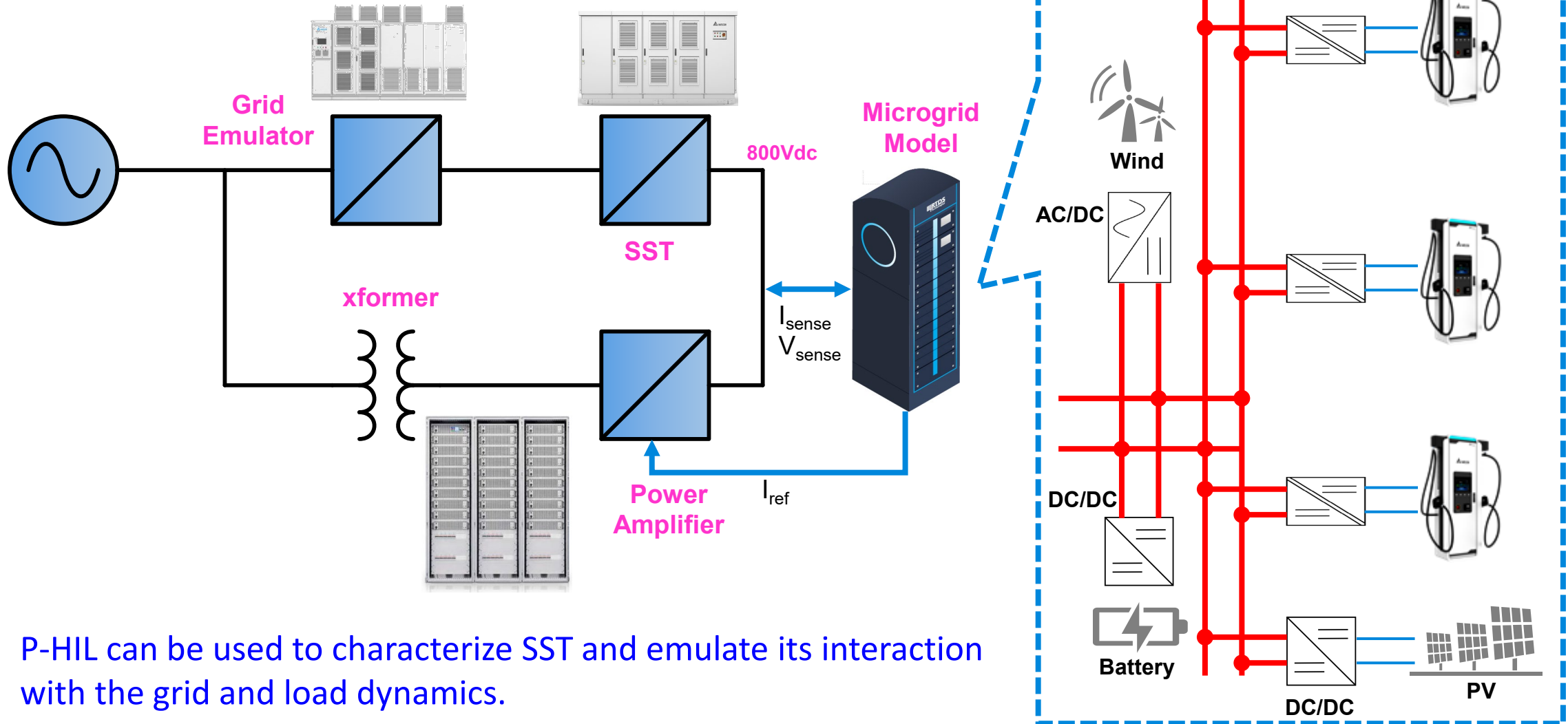


Texas 4-Hz weak grid oscillations: recorded voltage measurement at a WPP's point of interconnection.

1. Y. Cheng et al., "Real-World Sub-synchronous Oscillation Events in Power Grids With High Penetrations of Inverter-Based Resources," in *IEEE Transactions on Power Systems*, Jan. 2023.

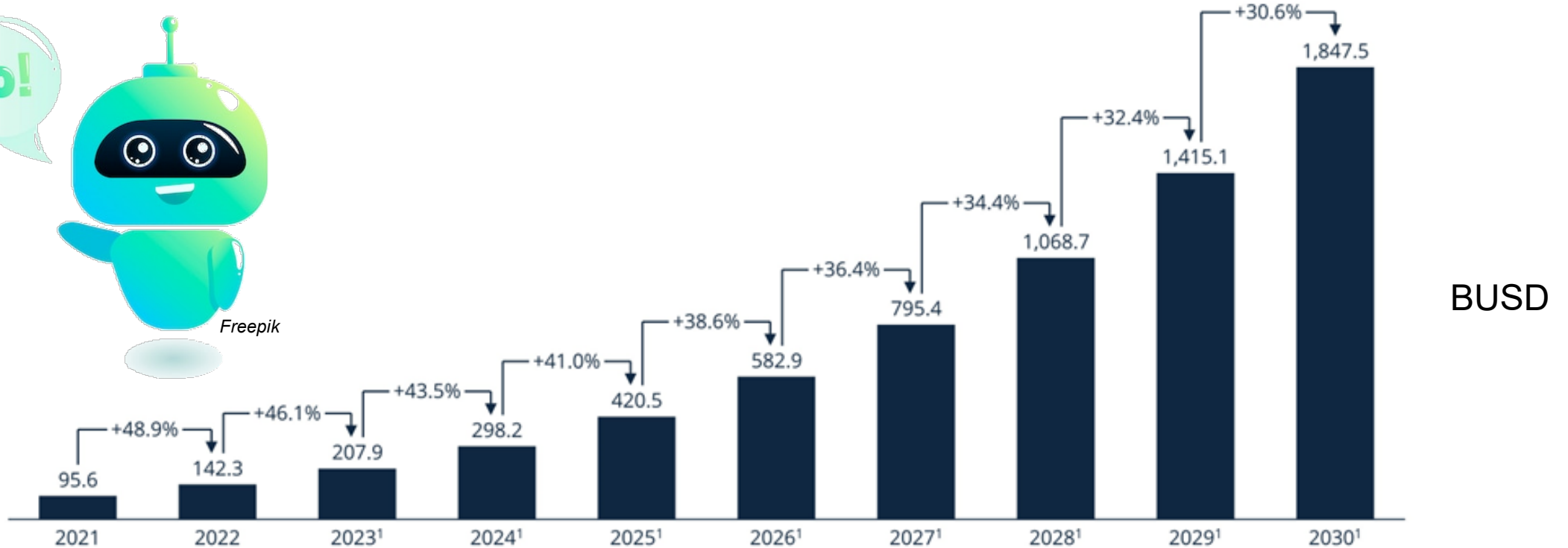
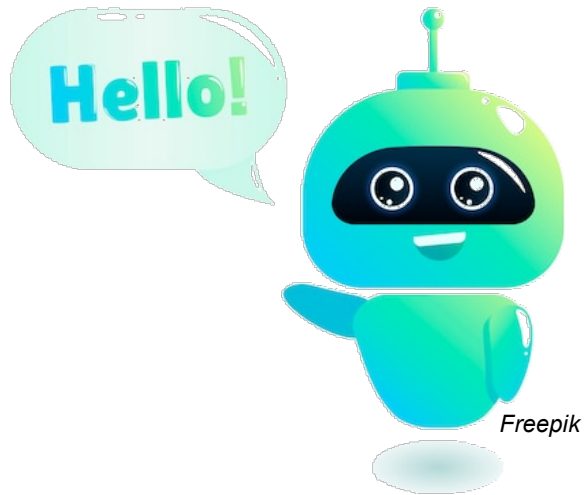
SST P-HIL Microgrid Simulation

Power Hardware in Loop SST Verification



- P-HIL can be used to characterize SST and emulate its interaction with the grid and load dynamics.

Global Artificial Intelligence Market

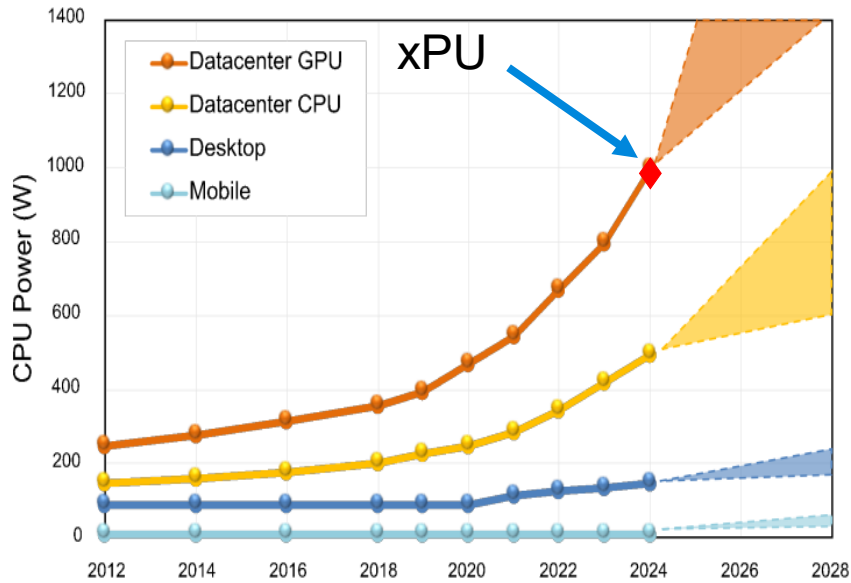


(1) Forecast
Sources: Next Move Strategy Consulting



The AI market is projected to reach US\$1.8 trillion by 2030

Datacenter Power Demand



Current Scenario

- 7 ~ 18 kW average enterprise rack power
- 30 kW ~ > 100 kW AI workloads rack power

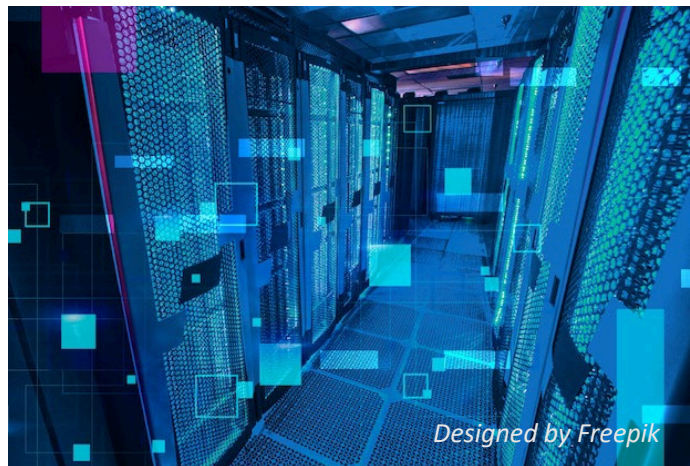
AI Workloads (2023)

- 54 GW total datacenter capacity (US ~ 19 GW)
- ~8% or 4.3 GW for AI workloads
 - 20% for training; 80% for inference

Projections for 2028

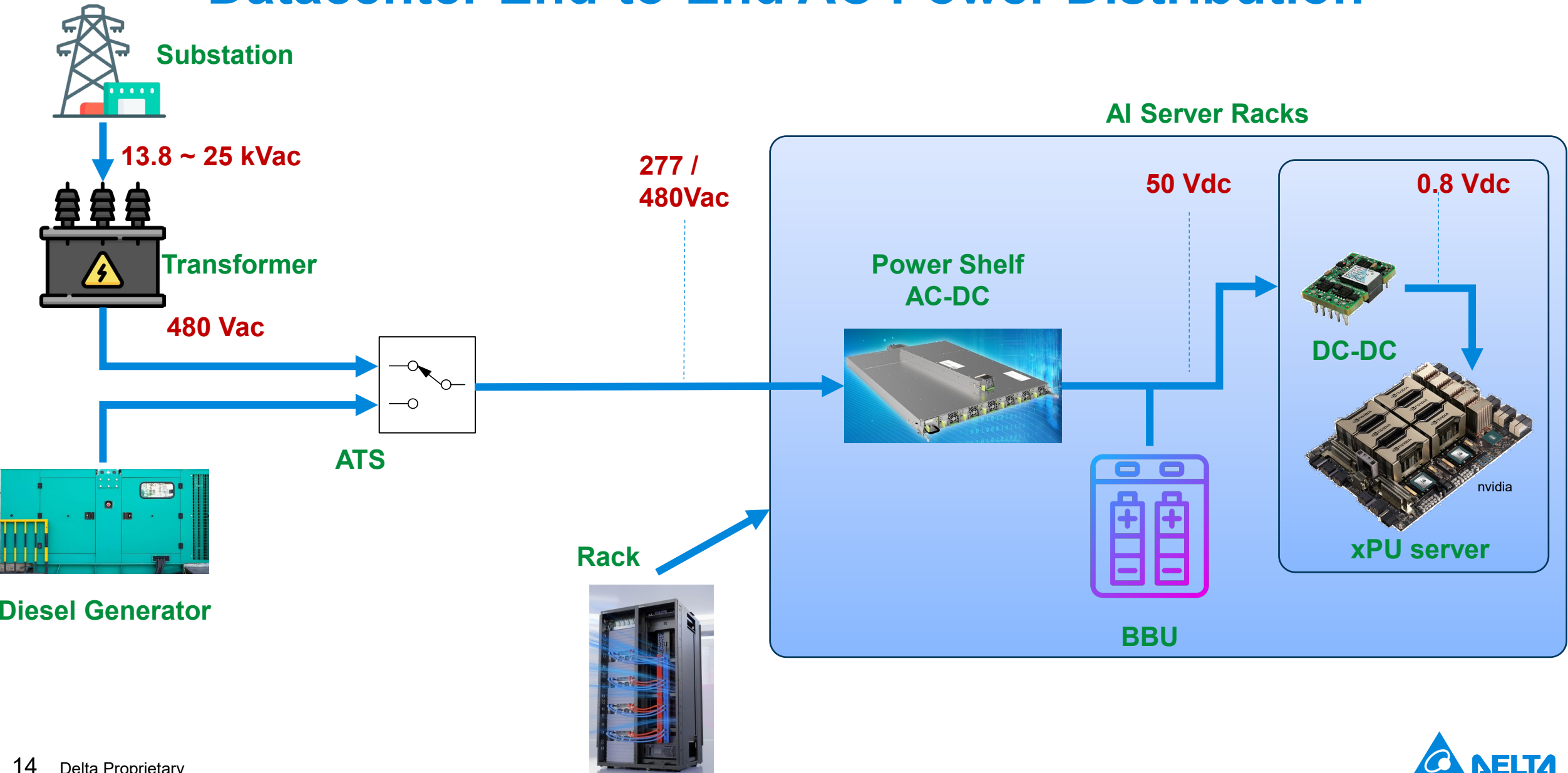
- 90 GW total datacenter capacity (US ~ 35 GW)
- 20 GW for AI workloads (20% data center consumption)
 - 15% for training; 85% for inference

1. K. Radhakrishnan, "Recent Advances in IVR Solutions for High Power Microprocessors," APEC2024

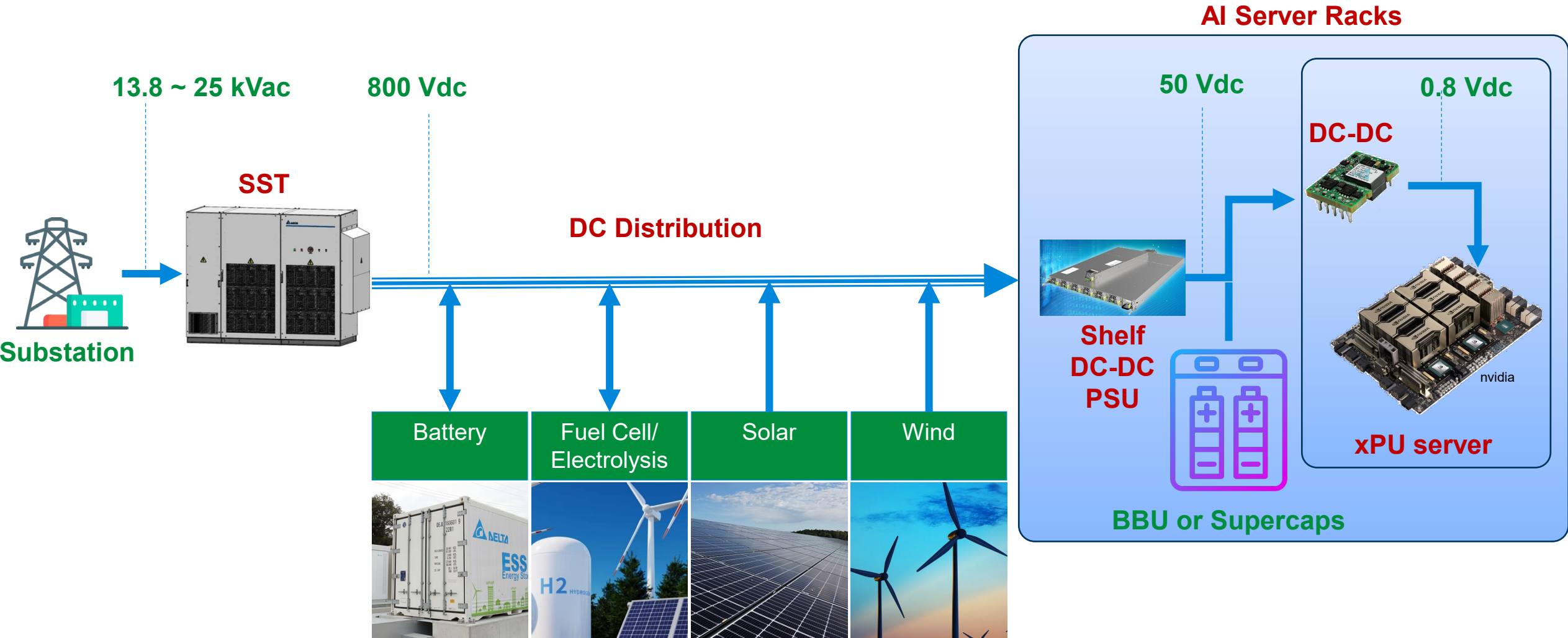


1. The AI Disruption Challenges and Guidance for Data Center Design, Schneider Electric

Datacenter End-to-End AC Power Distribution



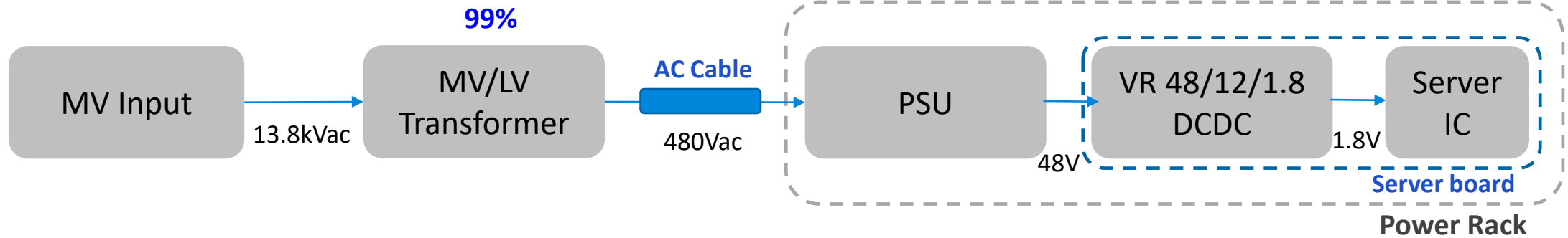
Next Generation Power Distribution



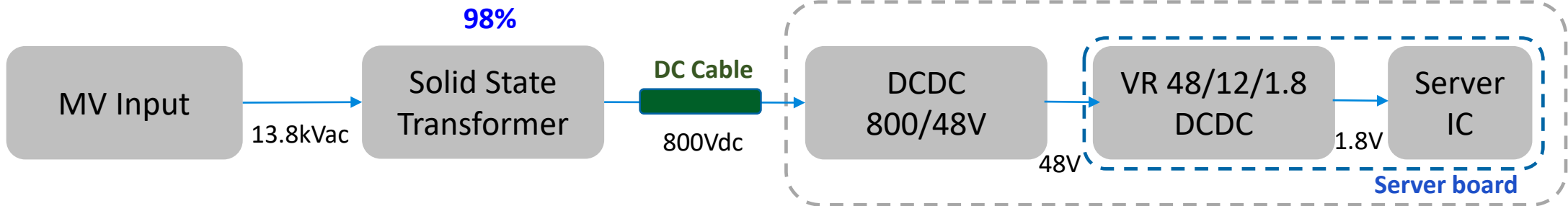
Distributed Energy Resources and Backup Power

Datacenter Power Architecture Comparison

Peak efficiency from MV to 48V: 95%



Peak efficiency from MV to 48V: >95%

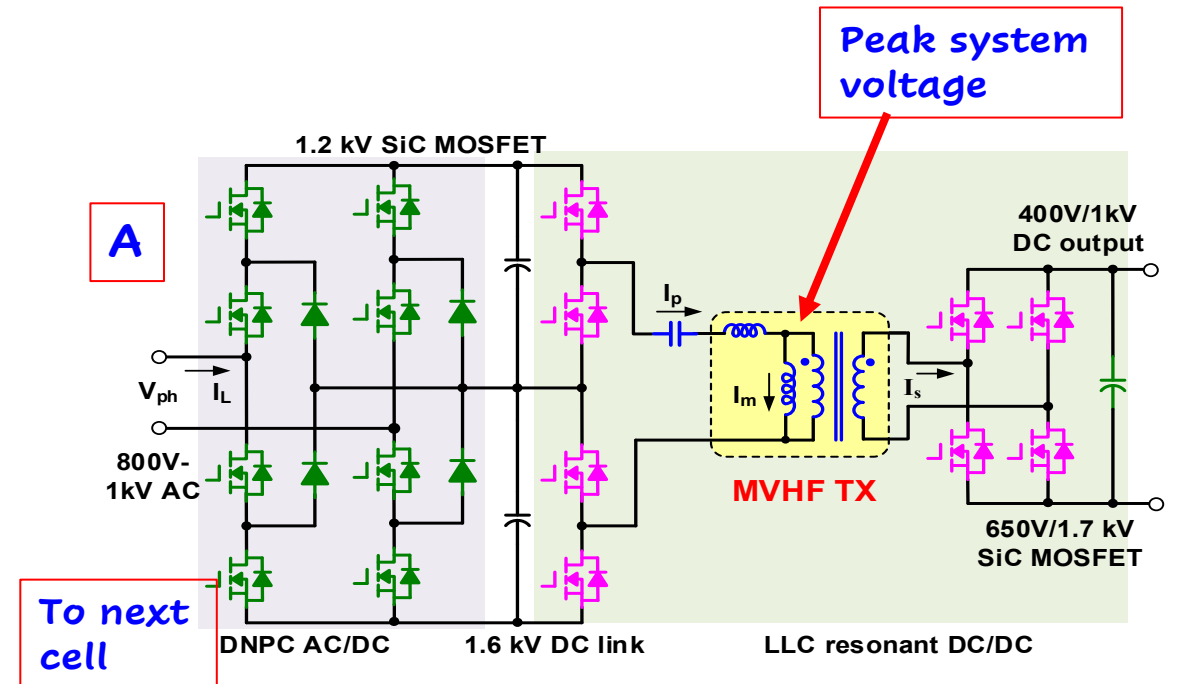
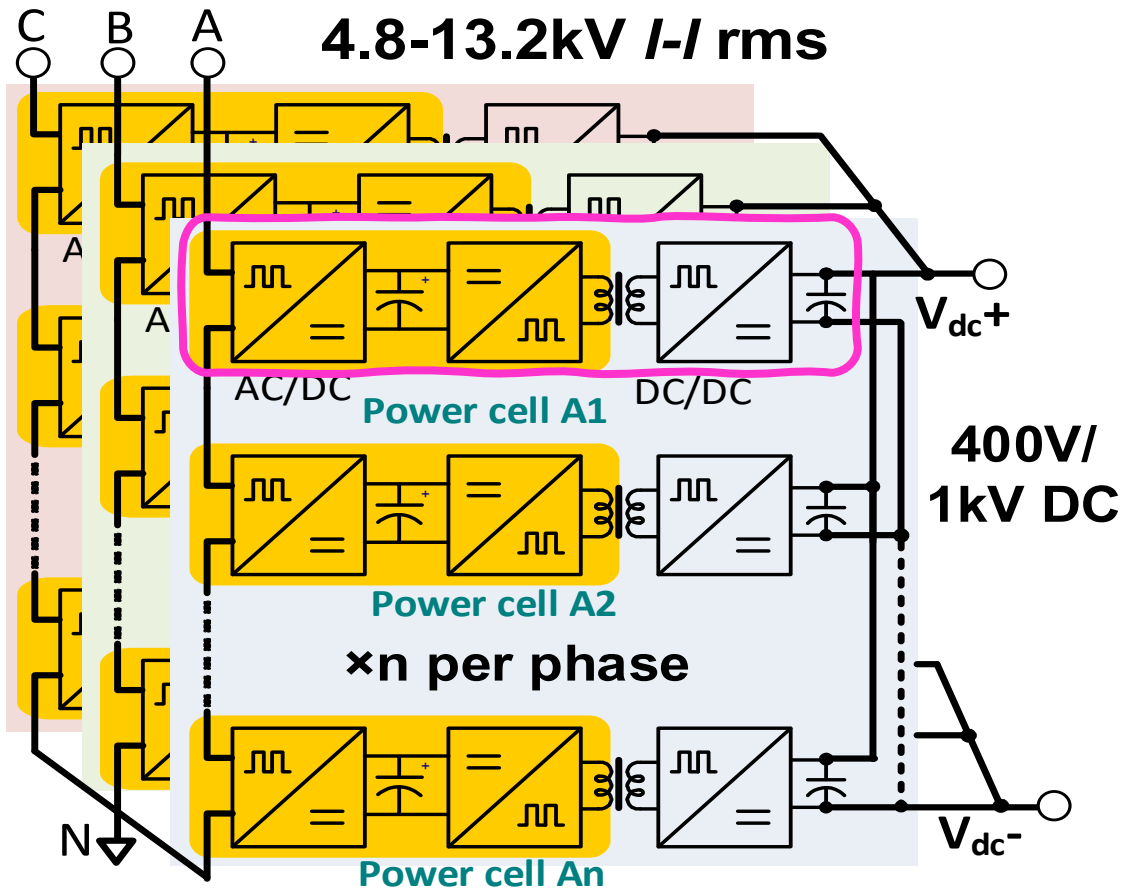


- Smaller footprint and lighter weight will save infrastructure capex
- The cost trend will favor more SST vs LFT in the long run

- Higher efficiency SST + DC distribution saves opex
- Modular & scalable without large LFT

- DC Bus provides RE/ESS integration capability
- SST also provides grid support functions

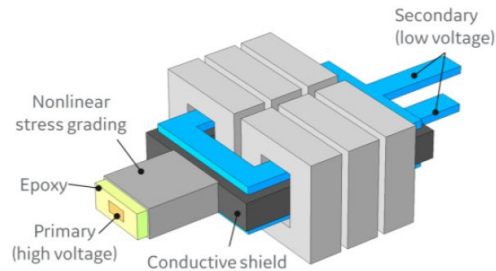
Key Component: MV Transformer



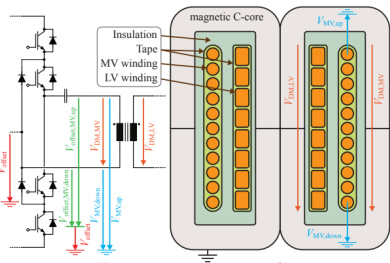
- High frequency transformer is key for insulation and power density (contradiction!)
- Challenges: concentrated e-fields, partial discharge, thermal handling, and manufacturing consistency

Medium-Voltage High-Frequency Transformer Technologies

Epoxy Filled HV or (HV and LV) winding



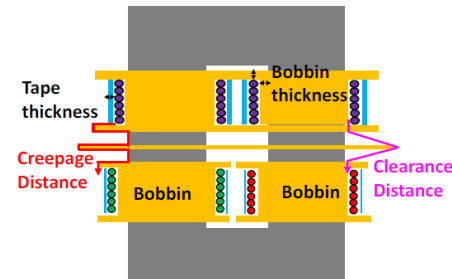
General Electric, 2018



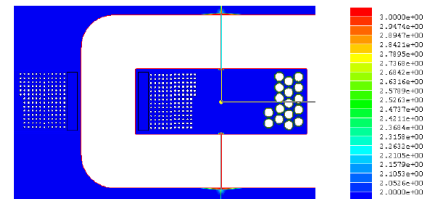
ETH, 2014

- Litz wire and epoxy combination defect
- Low turn to turn insulation capability

Separate HV and LV side through gap



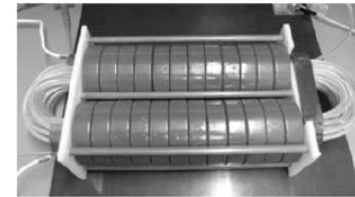
CPES, 2018



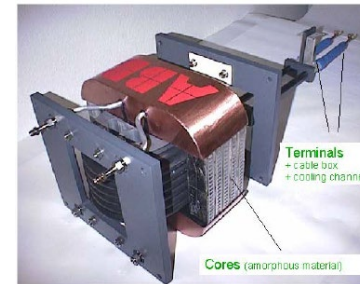
NCSU, 2010

- Magnetic inductance coupled with insulation

Coaxial type transformer



NCSU, 2011



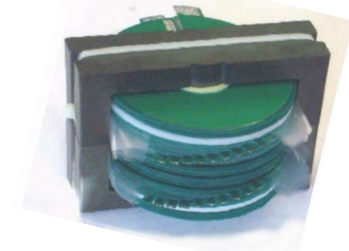
ABB, 2002

- Limited to 1:1 turns ratio

Oil Insulated Transformer



ABB, 2014

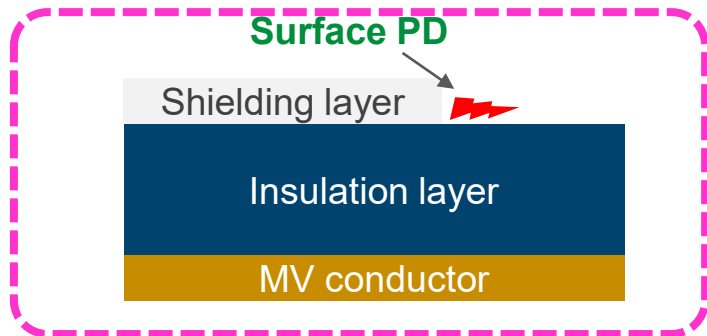
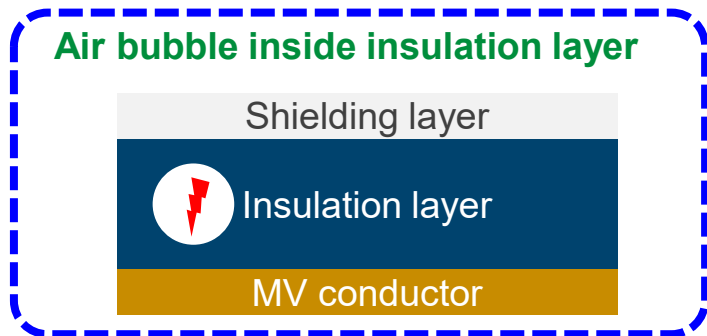
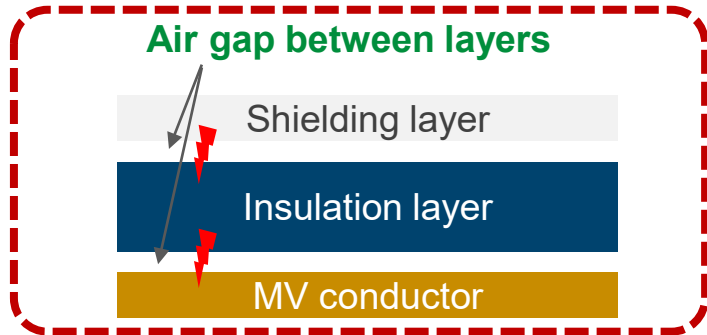


Aachen, 2014

- Dry type MV transformer preferred

Partial Discharge & Design Goals

Typical partial discharge defects



Air gap or air bubble defects can be well controlled through PCB process

Stress grading or terminal treatment is needed to reduce the surface PD

Property	Epoxy		PCB
	SilGel 612	50-3182NC	FR4-TG180
Dielectric Strength (kV/mm)	22	22	45
Thermal Conductivity (W/(m·K))	0.2	1.7	0.35
Viscosity (cps)	1000	15000	/

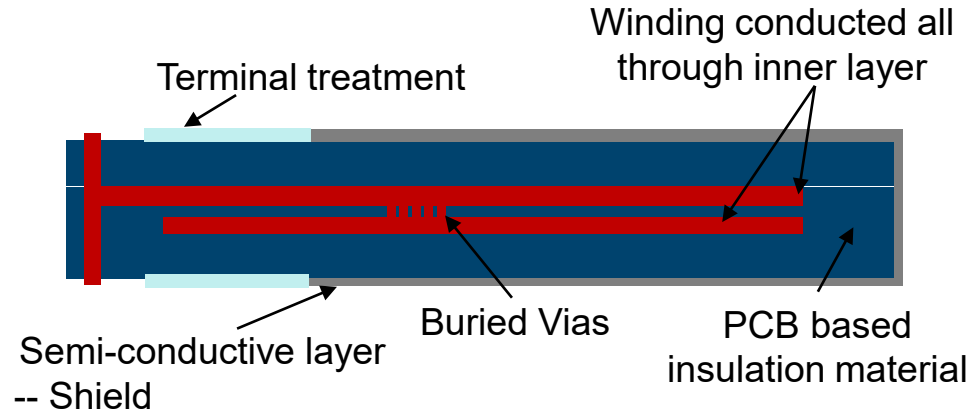
Dielectric selection & breakdown field strength

- Internal peak e-field < 20kV/mm
- Air peak e-field < 2kV/mm

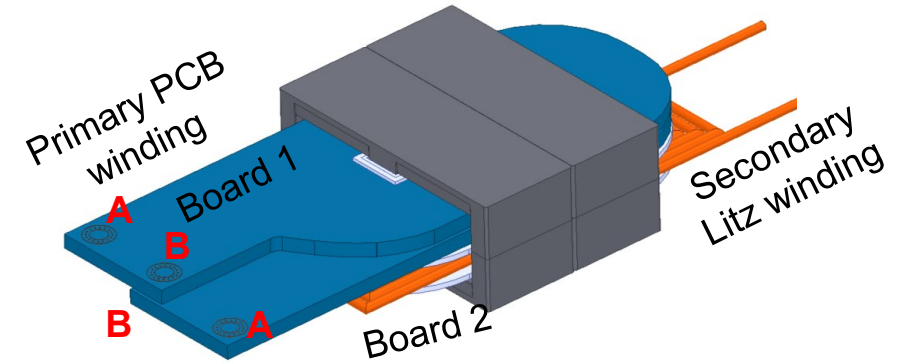
Goals

- No partial discharge in the operation range
- High efficiency and power density
- Easy manufacturing

Planar Structure MV Transformer Solution

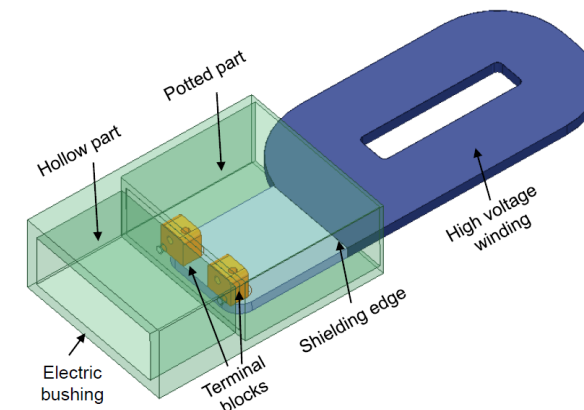


Cross-section View of High Voltage Winding Structure



Conceptual view of transformer prototype

- Inner layer for the HV conduction
- PCB based material (FR4) for insulation
- Buried vias (epoxy filled) for connect between inner layers
- Semi-conductive layer for shielding
- Stacked up windings for more turns
- Terminal treatment for surface PD and creepage requirement
- **Proposed solution constrains the e-field within the high voltage PCB winding. Winding and core area can be PD free**



Terminal potted with SilGel (Wacker 612)

Take Aways

SST is a key technology for emerging applications



Key components

HV WBG (>10 kV SiC) and UWBG power semiconductors

Passive components (inductors and capacitors)

High frequency transformers for MV insulation



Reliability

High operating temperatures and thermal cycling stresses

Failure mechanisms

Lifetime prediction and power device packaging

Harsh electrical and thermal stress on power and control circuits



Challenges

Cost

Limited power capability

Complex control requirements

Thermal management

Insulation

DC distribution fault, protection, grounding

Smarter. Greener. Together.

Thank You!

